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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	2400
Number of Logic Elements/Cells	10800
Total RAM Bits	163840
Number of I/O	404
Number of Gates	569952
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	560-LBGA Exposed Pad, Metal
Supplier Device Package	560-MBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv400e-8bg560c

Table 1: **Supported I/O Standards**

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Board Termination Voltage (V_{TT})
LVTTL	3.3	3.3	N/A	N/A
LVCMOS2	2.5	2.5	N/A	N/A
LVCMOS18	1.8	1.8	N/A	N/A
SSTL3 I & II	3.3	N/A	1.50	1.50
SSTL2 I & II	2.5	N/A	1.25	1.25
GTL	N/A	N/A	0.80	1.20
GTL+	N/A	N/A	1.0	1.50
HSTL I	1.5	N/A	0.75	0.75
HSTL III & IV	1.5	N/A	0.90	1.50
CTT	3.3	N/A	1.50	1.50
AGP-2X	3.3	N/A	1.32	N/A
PCI33_3	3.3	3.3	N/A	N/A
PCI66_3	3.3	3.3	N/A	N/A
BLVDS & LVDS	2.5	N/A	N/A	N/A
LVPECL	3.3	N/A	N/A	N/A

In addition to the CLK and CE control signals, the three flip-flops share a Set/Reset (SR). For each flip-flop, this signal can be independently configured as a synchronous Set, a synchronous Reset, an asynchronous Preset, or an asynchronous Clear.

The output buffer and all of the IOB control signals have independent polarity controls.

All pads are protected against damage from electrostatic discharge (ESD) and from over-voltage transients. After configuration, clamping diodes are connected to V_{CCO} with the exception of LVCMOS18, LVCMOS25, GTL, GTL+, LVDS, and LVPECL.

Optional pull-up, pull-down and weak-keeper circuits are attached to each pad. Prior to configuration all outputs not involved in configuration are forced into their high-impedance state. The pull-down resistors and the weak-keeper circuits are inactive, but I/Os can optionally be pulled up.

The activation of pull-up resistors prior to configuration is controlled on a global basis by the configuration mode pins. If the pull-up resistors are not activated, all the pins are in a high-impedance state. Consequently, external pull-up or pull-down resistors must be provided on pins required to be at a well-defined logic level prior to configuration.

All Virtex-E IOBs support IEEE 1149.1-compatible Boundary Scan testing.

Input Path

The Virtex-E IOB input path routes the input signal directly to internal logic and/ or through an optional input flip-flop.

An optional delay element at the D-input of this flip-flop eliminates pad-to-pad hold time. The delay is matched to the internal clock-distribution delay of the FPGA, and when used, assures that the pad-to-pad hold time is zero.

Each input buffer can be configured to conform to any of the low-voltage signalling standards supported. In some of these standards the input buffer utilizes a user-supplied threshold voltage, V_{REF}. The need to supply V_{REF} imposes constraints on which standards can be used in close proximity to each other. See **I/O Banking**.

There are optional pull-up and pull-down resistors at each user I/O input for use after configuration. Their value is in the range 50 – 100 kΩ.

Output Path

The output path includes a 3-state output buffer that drives the output signal onto the pad. The output signal can be routed to the buffer directly from the internal logic or through an optional IOB output flip-flop.

The 3-state control of the output can also be routed directly from the internal logic or through a flip-flip that provides synchronous enable and disable.

Each output driver can be individually programmed for a wide range of low-voltage signalling standards. Each output buffer can source up to 24 mA and sink up to 48 mA. Drive strength and slew rate controls minimize bus transients.

In most signalling standards, the output High voltage depends on an externally supplied V_{CCO} voltage. The need to supply V_{CCO} imposes constraints on which standards can be used in close proximity to each other. See **I/O Banking**.

An optional weak-keeper circuit is connected to each output. When selected, the circuit monitors the voltage on the pad and weakly drives the pin High or Low to match the input signal. If the pin is connected to a multiple-source signal, the weak keeper holds the signal in its last state if all drivers are disabled. Maintaining a valid logic level in this way eliminates bus chatter.

Since the weak-keeper circuit uses the IOB input buffer to monitor the input level, an appropriate V_{REF} voltage must be provided if the signalling standard requires one. The provision of this voltage must comply with the I/O banking rules.

I/O Banking

Some of the I/O standards described above require V_{CCO} and/or V_{REF} voltages. These voltages are externally supplied and connected to device pins that serve groups of IOBs, called banks. Consequently, restrictions exist about which I/O standards can be combined within a given bank.

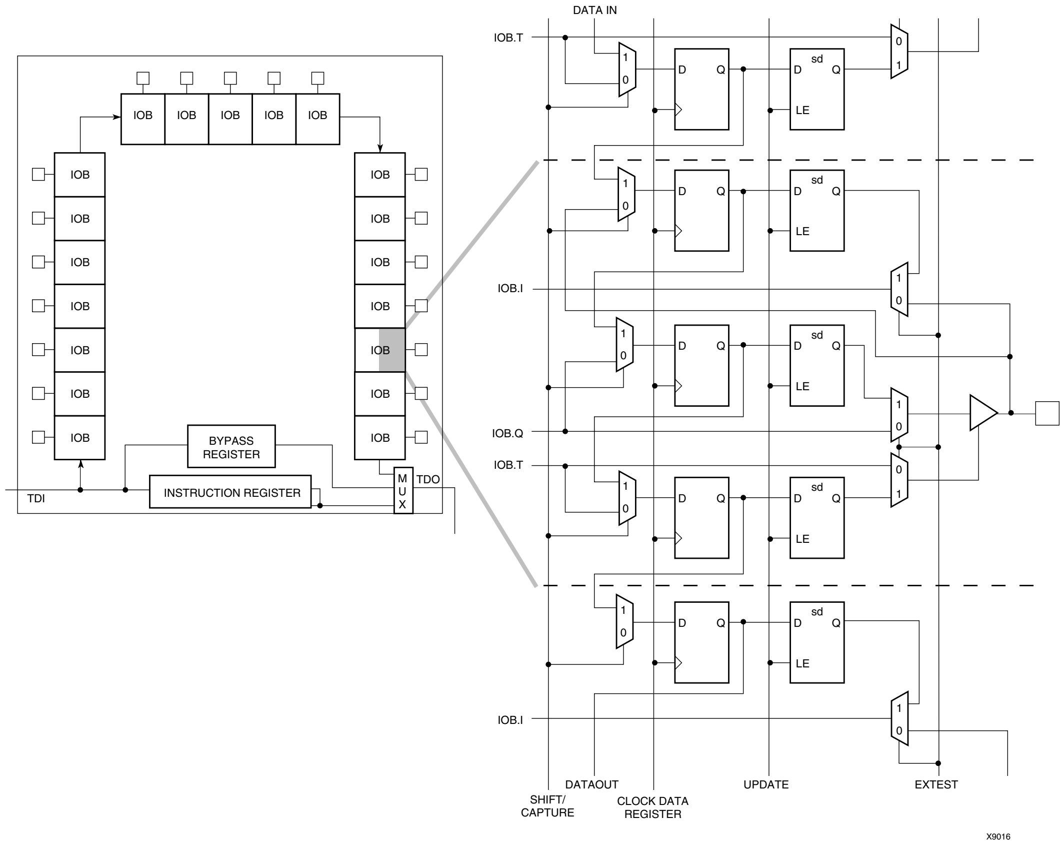

Figure 11: **Virtex-E Family Boundary Scan Logic**

Instruction Set

The Virtex-E series Boundary Scan instruction set also includes instructions to configure the device and read back configuration data (CFG_IN, CFG_OUT, and JSTART). The complete instruction set is coded as shown in Table 6..

Table 6: **Boundary Scan Instructions**

Boundary Scan Command	Binary Code(4:0)	Description
EXTEST	00000	Enables Boundary Scan EXTEST operation
SAMPLE/ PRELOAD	00001	Enables Boundary Scan SAMPLE/PRELOAD operation
USER1	00010	Access user-defined register 1
USER2	00011	Access user-defined register 2
CFG_OUT	00100	Access the configuration bus for read operations.

Table 6: **Boundary Scan Instructions *(Continued)***

Boundary Scan Command	Binary Code(4:0)	Description
CFG_IN	00101	Access the configuration bus for write operations.
INTEST	00111	Enables Boundary Scan INTEST operation
USERCODE	01000	Enables shifting out USER code
IDCODE	01001	Enables shifting out of ID Code
HIGHZ	01010	3-states output pins while enabling the Bypass Register
JSTART	01100	Clock the start-up sequence when StartupClk is TCK
BYPASS	11111	Enables BYPASS
RESERVED	All other codes	Xilinx reserved instructions

Input termination techniques include the following.

- None
- Parallel (Shunt)

These termination techniques can be applied in any combination. A generic example of each combination of termination methods appears in Figure 43.

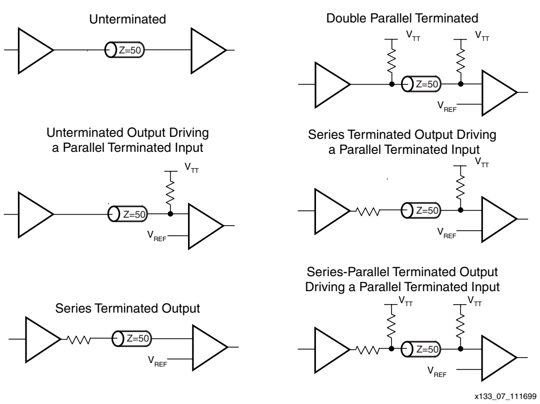

Figure 43: **Overview of Standard Input and Output Termination Methods**

Simultaneous Switching Guidelines

Ground bounce can occur with high-speed digital ICs when multiple outputs change states simultaneously, causing undesired transient behavior on an output, or in the internal logic. This problem is also referred to as the Simultaneous Switching Output (SSO) problem.

Ground bounce is primarily due to current changes in the combined inductance of ground pins, bond wires, and ground metallization. The IC internal ground level deviates from the external system ground level for a short duration (a few nanoseconds) after multiple outputs change state simultaneously.

Ground bounce affects stable Low outputs and all inputs because they interpret the incoming signal by comparing it to the internal ground. If the ground bounce amplitude exceeds the actual instantaneous noise margin, then a non-changing input can be interpreted as a short pulse with a polarity opposite to the ground bounce.

Table 21 provides guidelines for the maximum number of simultaneously switching outputs allowed per output power/ground pair to avoid the effects of ground bounce. See Table 22 for the number of effective output power/ground pairs for each Virtex-E device and package combination.

Table 21: **Guidelines for Max Number of Simultaneously Switching Outputs per Power/Ground Pair**

Standard	Package		
	BGA, CS, FGA	HQ	PQ, TQ
LVTTL Slow Slew Rate, 2 mA drive	68	49	36
LVTTL Slow Slew Rate, 4 mA drive	41	31	20
LVTTL Slow Slew Rate, 6 mA drive	29	22	15
LVTTL Slow Slew Rate, 8 mA drive	22	17	12
LVTTL Slow Slew Rate, 12 mA drive	17	12	9
LVTTL Slow Slew Rate, 16 mA drive	14	10	7
LVTTL Slow Slew Rate, 24 mA drive	9	7	5
LVTTL Fast Slew Rate, 2 mA drive	40	29	21
LVTTL Fast Slew Rate, 4 mA drive	24	18	12
LVTTL Fast Slew Rate, 6 mA drive	17	13	9
LVTTL Fast Slew Rate, 8 mA drive	13	10	7
LVTTL Fast Slew Rate, 12 mA drive	10	7	5
LVTTL Fast Slew Rate, 16 mA drive	8	6	4
LVTTL Fast Slew Rate, 24 mA drive	5	4	3
LVCMOS	10	7	5
PCI	8	6	4
GTL	4	4	4
GTL+	4	4	4

Application Examples

Creating a design with the SelectI/O features requires the instantiation of the desired library symbol within the design code. At the board level, designers need to know the termination techniques required for each I/O standard.

This section describes some common application examples illustrating the termination techniques recommended by each of the standards supported by the SelectI/O features.

Termination Examples

Circuit examples involving typical termination techniques for each of the SelectI/O standards follow. For a full range of accepted values for the DC voltage specifications for each standard, refer to the table associated with each figure.

The resistors used in each termination technique example and the transmission lines depicted represent board level components and are not meant to represent components on the device.

GTL

A sample circuit illustrating a valid termination technique for GTL is shown in Figure 44.

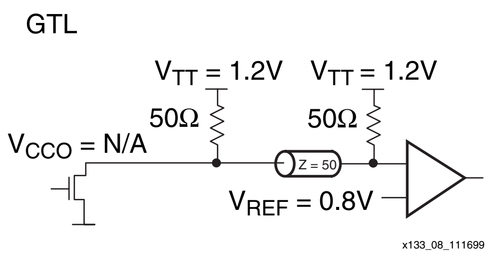

Figure 44: **Terminated GTL**

Table 23 lists DC voltage specifications.

Table 23: **GTL Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	-	N/A	-
$V_{REF} = N \times V_{TT}$[1]	0.74	0.8	0.86
V_{TT}	1.14	1.2	1.26
$V_{IH} = V_{REF} + 0.05$	0.79	0.85	-
$V_{IL} = V_{REF} - 0.05$	-	0.75	0.81
V_{OH}	-	-	-
V_{OL}	-	0.2	0.4
I_{OH} at V_{OH}(mA)	-	-	-
I_{OL}at V_{OL}(mA) at 0.4V	32	-	-
I_{OL}at V_{OL}(mA) at 0.2V	-	-	40

Notes:

1. N must be greater than or equal to 0.653 and less than or equal to 0.68.

GTL+

A sample circuit illustrating a valid termination technique for GTL+ appears in Figure 45. DC voltage specifications appear in Table 24.

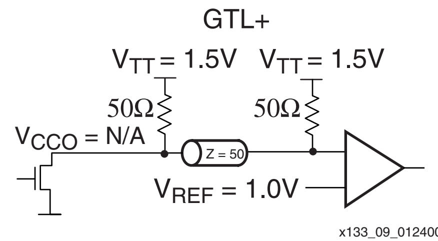

Figure 45: **Terminated GTL+**

Table 24: **GTL+ Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	-	-	-
$V_{REF} = N \times V_{TT}$[1]	0.88	1.0	1.12
V_{TT}	1.35	1.5	1.65
$V_{IH} = V_{REF} + 0.1$	0.98	1.1	-
$V_{IL} = V_{REF} - 0.1$	-	0.9	1.02
V_{OH}	-	-	-
V_{OL}	0.3	0.45	0.6
I_{OH} at V_{OH} (mA)	-	-	-
I_{OL}at V_{OL} (mA) at 0.6V	36	-	-
I_{OL}at V_{OL} (mA) at 0.3V	-	-	48

Notes:

1. N must be greater than or equal to 0.653 and less than or equal to 0.68.

LVTTL

LVTTL requires no termination. DC voltage specifications appears in Table 34.

Table 34: **LVTTL Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	2.0	-	3.6
V_{IL}	–0.5	-	0.8
V_{OH}	2.4	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–24	-	-
I_{OL} at V_{OL} (mA)	24	-	-

Notes:
1. Note: V_{OL} and V_{OH} for lower drive currents sample tested.

LVCMOS2

LVCMOS2 requires no termination. DC voltage specifications appear in Table 35.

Table 35: **LVCMOS2 Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.3	2.5	2.7
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	1.7	-	3.6
V_{IL}	–0.5	-	0.7
V_{OH}	1.9	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–12	-	-
I_{OL} at V_{OL} (mA)	12	-	-

LVCMOS18

LVCMOS18 does not require termination. Table 36 lists DC voltage specifications.

Table 36: **LVCMOS18 Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	1.70	1.80	1.90
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	0.65 x V_{CCO}	-	1.95
V_{IL}	– 0.5	-	0.2 x V_{CCO}
V_{OH}	V_{CCO} – 0.4	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL} at V_{OL} (mA)	8	-	-

AGP-2X

The specification for the AGP-2X standard does not document a recommended termination technique. DC voltage specifications appear in Table 37.

Table 37: **AGP-2X Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
$V_{REF} = N \times V_{CCO}^{(1)}$	1.17	1.32	1.48
V_{TT}	-	-	-
$V_{IH} = V_{REF} + 0.2$	1.37	1.52	-
$V_{IL} = V_{REF} – 0.2$	-	1.12	1.28
$V_{OH} = 0.9 \times V_{CCO}$	2.7	3.0	-
$V_{OL} = 0.1 \times V_{CCO}$	-	0.33	0.36
I_{OH} at V_{OH} (mA)	Note 2	-	-
I_{OL} at V_{OL} (mA)	Note 2	-	-

Notes:
1. N must be greater than or equal to 0.39 and less than or equal to 0.41.
2. Tested according to the relevant specification.

Table 42: **Input Library Macros**

Name	Inputs	Outputs
IBUFDS_FD_LVDS	I, IB, C	Q
IBUFDS_FDE_LVDS	I, IB, CE, C	Q
IBUFDS_FDC_LVDS	I, IB, C, CLR	Q
IBUFDS_FDCE_LVDS	I, IB, CE, C, CLR	Q
IBUFDS_FDP_LVDS	I, IB, C, PRE	Q
IBUFDS_FDPE_LVDS	I, IB, CE, C, PRE	Q
IBUFDS_FDR_LVDS	I, IB, C, R	Q
IBUFDS_FDRE_LVDS	I, IB, CE, C, R	Q
IBUFDS_FDS_LVDS	I, IB, C, S	Q
IBUFDS_FDSE_LVDS	I, IB, CE, C, S	Q
IBUFDS_LD_LVDS	I, IB, G	Q
IBUFDS_LDE_LVDS	I, IB, GE, G	Q
IBUFDS_LDC_LVDS	I, IB, G, CLR	Q
IBUFDS_LDCE_LVDS	I, IB, GE, G, CLR	Q
IBUFDS_LDP_LVDS	I, IB, G, PRE	Q
IBUFDS_LDPE_LVDS	I, IB, GE, G, PRE	Q

Creating LVDS Output Buffers

LVDS output buffers can be placed in a wide number of IOB locations. The exact locations are dependent on the package used. The Virtex-E package information lists the possible locations as IO_L#P for the P-side and IO_L#N for the N-side, where # is the pair number.

HDL Instantiation

Both output buffers are required to be instantiated in the design and placed on the correct IO_L#P and IO_L#N locations. The IOB must have the same net source the following pins, clock (C), set/reset (SR), output (O), output clock enable (OCE). In addition, the output (O) pins must be inverted with respect to each other, and if output registers are used, the INIT states must be opposite values (one HIGH and one LOW). Failure to follow these rules leads to DRC errors in software.

VHDL Instantiation

```
data0_p   : OBUF_LVDS port map
(I=>data_int(0),    O=>data_p(0));

data0_inv: INV       port map
(I=>data_int(0),    O=>data_n_int(0));

data0_n   : OBUF_LVDS port map
(I=>data_n_int(0), O=>data_n(0));
```

Verilog Instantiation

```
OBUF_LVDS data0_p   (.I(data_int[0]),
.O(data_p[0]));

INV       data0_inv (.I(data_int[0],
.O(data_n_int[0]);

OBUF_LVDS data0_n   (.I(data_n_int[0]),
.O(data_n[0]));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the output buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data_p<0> LOC = D28; # IO_L0P

NET data_n<0> LOC = B29; # IO_L0N
```

Synchronous vs. Asynchronous Outputs

If the outputs are synchronous (registered in the IOB) then any IO_L#P|N pair can be used. If the outputs are asynchronous (no output register), then they must use one of the pairs that are part of the same IOB group at the end of a ROW or COLUMN in the device.

The LVDS pairs that can be used as asynchronous outputs are listed in the Virtex-E pinout tables. Some pairs are marked as asynchronous-capable for all devices in that package, and others are marked as available only for that device in the package. If the device size might change at some point in the product lifetime, then only the common pairs for all packages should be used.

Adding an Output Register

All LVDS buffers can have an output register in the IOB. The output registers must be in both the P-side and N-side IOBs. All the normal IOB register options are available (FD, FDE, FDC, FDCE, FDP, FDPE, FDR, FDRE, FDS, FDSE, LD, LDE, LDC, LDCE, LDP, LDPE). The register elements can be inferred or explicitly instantiated in the HDL code.

Special care must be taken to insure that the D pins of the registers are inverted and that the INIT states of the registers are opposite. The clock pin (C), clock enable (CE) and set/reset (CLR/PRE or S/R) pins must connect to the same source. Failure to do this leads to a DRC error in the software.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the "map -pr [i|o|b]" where "i" is inputs only, "o" is outputs only and "b" is both inputs and outputs.

To improve design coding times VHDL and Verilog synthesis macro libraries have been developed to explicitly create these structures. The output library macros are listed in Table 43. The O and OB inputs to the macros are the external net connections.

Virtex-E Data Sheet

The Virtex-E Data Sheet contains the following modules:

- DS022-1, Virtex-E 1.8V FPGAs:
  Introduction and Ordering Information (Module 1)
- DS022-2, Virtex-E 1.8V FPGAs:
  Functional Description (Module 2)
- DS022-3, Virtex-E 1.8V FPGAs:
  DC and Switching Characteristics (Module 3)
- DS022-4, Virtex-E 1.8V FPGAs:
  Pinout Tables (Module 4)

Virtex-E Electrical Characteristics

Definition of Terms

Electrical and switching characteristics are specified on a per-speed-grade basis and can be designated as Advance, Preliminary, or Production. Each designation is defined as follows:

Advance: These speed files are based on simulations only and are typically available soon after device design specifications are frozen. Although speed grades with this designation are considered relatively stable and conservative, some under-reporting might still occur.

Preliminary: These speed files are based on complete ES (engineering sample) silicon characterization. Devices and speed grades with this designation are intended to give a better indication of the expected performance of production silicon. The probability of under-reporting delays is greatly reduced as compared to Advance data.

Production: These speed files are released once enough production silicon of a particular device family member has been characterized to provide full correlation between speed files and devices over numerous production lots. There is no under-reporting of delays, and customers receive formal notification of any subsequent changes. Typically, the slowest speed grades transition to Production before faster speed grades.

All specifications are representative of worst-case supply voltage and junction temperature conditions. The parameters included are common to popular designs and typical applications. Contact the factory for design considerations requiring more detailed information.

Table 1 correlates the current status of each Virtex-E device with a corresponding speed file designation.

Table 1: **Virtex-E Device Speed Grade Designations**

Device	Speed Grade Designations		
	Advance	**Preliminary**	**Production**
XCV50E			–8, –7, –6
XCV100E			–8, –7, –6
XCV200E			–8, –7, –6
XCV300E			–8, –7, –6
XCV400E			–8, –7, –6
XCV600E			–8, –7, –6
XCV1000E			–8, –7, –6
XCV1600E			–8, –7, –6
XCV2000E			–8, –7, –6
XCV2600E			–8, –7, –6
XCV3200E			–8, –7, –6

All specifications are subject to change without notice.

DC Characteristics Over Recommended Operating Conditions

Symbol	Description		Device	Min	Max	Units
V_{DRINT}	Data Retention V_{CCINT} Voltage (below which configuration data might be lost)		All	1.5		V
V_{DRIO}	Data Retention V_{CCO} Voltage (below which configuration data might be lost)		All	1.2		V
I_{CCINTQ}	Quiescent V_{CCINT} supply current (Note 1)		XCV50E		200	mA
			XCV100E		200	mA
			XCV200E		300	mA
			XCV300E		300	mA
			XCV400E		300	mA
			XCV600E		400	mA
			XCV1000E		500	mA
			XCV1600E		500	mA
			XCV2000E		500	mA
			XCV2600E		500	mA
			XCV3200E		500	mA
I_{CCOQ}	Quiescent V_{CCO} supply current (Note 1)		XCV50E		2	mA
			XCV100E		2	mA
			XCV200E		2	mA
			XCV300E		2	mA
			XCV400E		2	mA
			XCV600E		2	mA
			XCV1000E		2	mA
			XCV1600E		2	mA
			XCV2000E		2	mA
			XCV2600E		2	mA
			XCV3200E		2	mA
I_L	Input or output leakage current		All	–10	+10	μA
C_{IN}	Input capacitance (sample tested)	BGA, PQ, HQ, packages	All		8	pF
I_{RPU}	Pad pull-up (when selected) @ V_{in} = 0 V, V_{CCO} = 3.3 V (sample tested)		All	Note 2	0.25	mA
I_{RPD}	Pad pull-down (when selected) @ V_{in} = 3.6 V (sample tested)			Note 2	0.25	mA

Notes:
1. With no output current loads, no active input pull-up resistors, all I/O pins 3-stated and floating.
2. Internal pull-up and pull-down resistors guarantee valid logic levels at unconnected input pins. These pull-up and pull-down resistors do not guarantee valid logic levels when input pins are connected to other circuits.

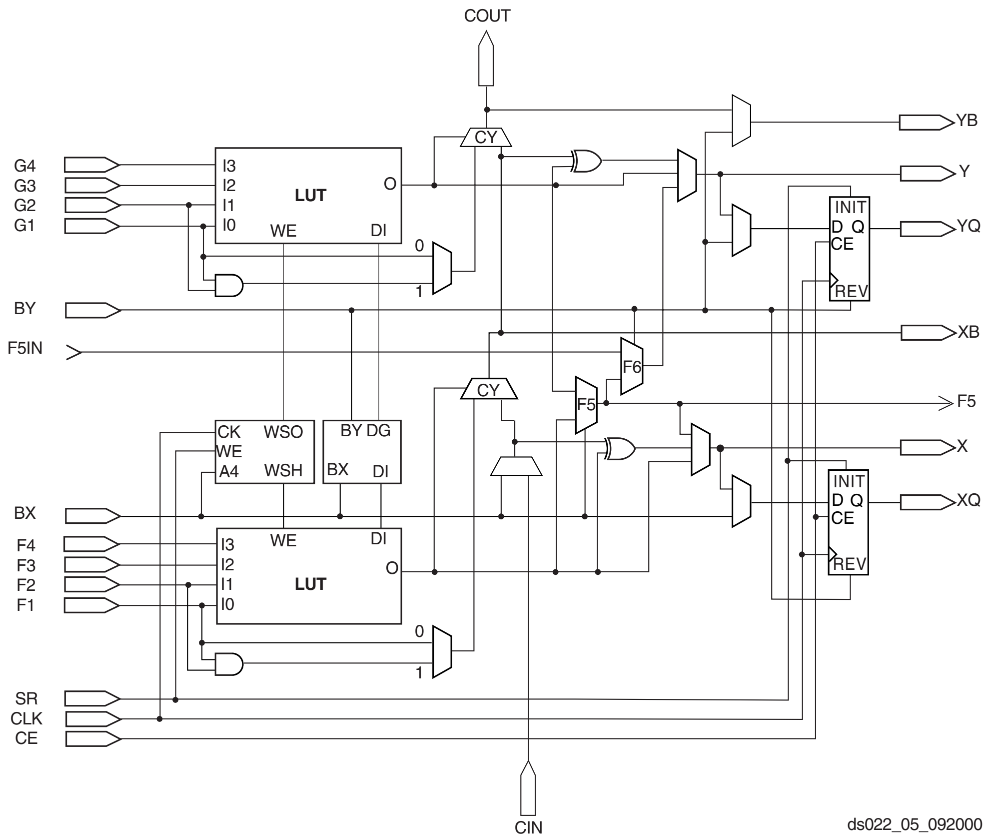

Figure 2: **Detailed View of Virtex-E Slice**

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
4	IO_L70N_Y	AK4
4	IO_L71P_YY	AJ5
4	IO_L71N_YY	AH6
4	IO_VREF_L72P_YY	AL4
4	IO_L72N_YY	AK5
4	IO_L73P_Y	AJ6
4	IO_L73N_Y	AH7
4	IO_L74P_YY	AL5
4	IO_L74N_YY	AK6
4	IO_VREF_L75P_YY	AJ7
4	IO_L75N_YY	AL6
4	IO_L76P_Y	AH9
4	IO_L76N_Y	AJ8
4	IO_VREF_L77P_Y	AK8[1]
4	IO_L77N_Y	AJ9
4	IO_VREF_L78P_YY	AL8
4	IO_L78N_YY	AK9
4	IO_L79P_YY	AK10
4	IO_L79N_YY	AL10
4	IO_L80P_YY	AH12
4	IO_L80N_YY	AK11
4	IO_L81P_YY	AJ12
4	IO_L81N_YY	AK12
4	IO_L82P_YY	AH13
4	IO_L82N_YY	AJ13
4	IO_VREF_L83P_YY	AL13
4	IO_L83N_YY	AK14
4	IO_L84P_Y	AH14
4	IO_L84N_Y	AJ14
4	IO_VREF_L85P_Y	AK15[2]
4	IO_L85N_Y	AJ15
4	IO_LVDS_DLL_L86P	AH15
5	GCK1	AK16
5	IO	AH20
5	IO	AJ19

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
5	IO	AJ23
5	IO	AJ24
5	IO_LVDS_DLL_L86N	AL17
5	IO_L87P_Y	AK17
5	IO_VREF_L87N_Y	AJ17[2]
5	IO_L88P_Y	AH17
5	IO_L88N_Y	AK18
5	IO_L89P_YY	AL19
5	IO_VREF_L89N_YY	AJ18
5	IO_L90P_YY	AH18
5	IO_L90N_YY	AL20
5	IO_L91P_YY	AK20
5	IO_L91N_YY	AH19
5	IO_L92P_YY	AJ20
5	IO_L92N_YY	AK21
5	IO_L93P_YY	AJ21
5	IO_L93N_YY	AL22
5	IO_L94P_YY	AJ22
5	IO_VREF_L94N_YY	AK23
5	IO_L95P_Y	AH22
5	IO_VREF_L95N_Y	AL24[1]
5	IO_L96P_Y	AK24
5	IO_L96N_Y	AH23
5	IO_L97P_YY	AK25
5	IO_VREF_L97N_YY	AJ25
5	IO_L98P_YY	AL26
5	IO_L98N_YY	AK26
5	IO_L99P_Y	AH25
5	IO_L99N_Y	AL27
5	IO_L100P_YY	AJ26
5	IO_VREF_L100N_YY	AK27
5	IO_L101P_YY	AH26
5	IO_L101N_YY	AL28
5	IO_L102P_Y	AJ27
5	IO_L102N_Y	AK28

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
4	IO_L43P_Y	P12
4	IO_VREF_L43N_Y	R13[2]
4	IO_L44P_YY	N12
4	IO_L44N_YY	T13
4	IO_VREF_L45P_YY	T12
4	IO_L45N_YY	P11
4	IO_L46P_Y	R12
4	IO_L46N_Y	N11
4	IO_VREF_L47P_YY	T11[1]
4	IO_L47N_YY	M11
4	IO_L48P_YY	R11
4	IO_L48N_YY	T10
4	IO_L49P_Y	R10
4	IO_L49N_Y	M10
4	IO_VREF_L50P_Y	P9
4	IO_L50N_Y	T9
4	IO_L51P_Y	N10
4	IO_L51N_Y	R9
4	IO_LVDS_DLL_L52P	N9
5	GCK1	R8
5	IO	N7
5	IO	T7
5	IO_LVDS_DLL_L52N	T8
5	IO_L53P_Y	R7
5	IO_VREF_L53N_Y	P8
5	IO_L54P_Y	P7
5	IO_L54N_Y	T6
5	IO_L55P_YY	M7
5	IO_L55N_YY	R6
5	IO_L56P_YY	P6
5	IO_VREF_L56N_YY	R5[1]
5	IO_L57P_Y	N6
5	IO_L57N_Y	T5
5	IO_L58P_YY	M6

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
5	IO_VREF_L58N_YY	T4
5	IO_L59P_YY	T3
5	IO_L59N_YY	P5
5	IO_VREF_L60P_Y	T2[2]
5	IO_L60N_Y	N5
6	IO_L61N_YY	M3
6	IO_L61P_YY	R1
6	IO_L62N	M4
6	IO_VREF_L62P	N2[2]
6	IO_L63N_YY	L5
6	IO_L63P_YY	P1
6	IO_VREF_L64N_Y	N1
6	IO_L64P_Y	L3
6	IO_L65N	M2
6	IO_L65P	L4
6	IO_VREF_L66N_Y	M1[1]
6	IO_L66P_Y	K4
6	IO_L67N_YY	L2
6	IO_L67P_YY	L1
6	IO_L68N	K3
6	IO_L68P	K1
6	IO_L69N_YY	K2
6	IO_L69P_YY	K5
6	IO_VREF_L70N_Y	J3
6	IO_L70P_Y	J1
6	IO_L71N	J4
6	IO_L71P	H1
6	IO	J2
7	IO	C2
7	IO_L72N_YY	G1
7	IO_L72P_YY	H4
7	IO_L73N	G5
7	IO_L73P	H2

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
NA	GND	K11
NA	GND	K10
NA	GND	K9
NA	GND	K8
NA	GND	K7
NA	GND	K6
NA	GND	J10
NA	GND	J9
NA	GND	J8
NA	GND	J7
NA	GND	H10
NA	GND	H9
NA	GND	H8
NA	GND	H7
NA	GND	G11
NA	GND	G10
NA	GND	G9
NA	GND	G8
NA	GND	G7
NA	GND	G6
NA	GND	F11
NA	GND	F10
NA	GND	F7
NA	GND	F6
NA	GND	B15
NA	GND	B2
NA	GND	A16
NA	GND	A1

Notes:
1. V_{REF} or I/O option only in the XCV100E, 200E, 300E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV200E, 300E; otherwise, I/O option only.

FG256 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs than can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 17: **FG256 Differential Pin Pair Summary XCV50E, XCV100E, XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	N8	N9	NA	IO_DLL_L52P
1	5	R8	T8	NA	IO_DLL_L52N
2	1	C9	A8	NA	IO_DLL_L8P
3	0	B8	A7	NA	IO_DLL_L8N
IO LVDS Total Pairs: 83, Asynchronous Outputs: 35					
0	0	A3	C5	7	VREF
1	0	E6	D5	√	-
2	0	A4	B4	√	VREF
3	0	B5	D6	2	-
4	0	A5	C6	√	VREF
5	0	C7	B6	√	-
6	0	C8	D7	1	-
7	0	A6	B7	1	VREF
8	1	A8	A7	NA	IO_LVDS_DLL
9	1	A9	D9	2	-
10	1	B9	E10	1	VREF
11	1	D10	A10	1	-
12	1	A11	C10	√	-
13	1	E11	B11	√	VREF
14	1	D11	A12	2	-
15	1	C11	A13	√	VREF
16	1	D12	B12	√	-
17	1	C12	A14	7	VREF
18	1	B13	C13	√	CS

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
1	IO_L40P_YY	D20
1	IO_L41N_YY	F19
1	IO_VREF_L41P_YY	C21
1	IO_L42N_YY	B22
1	IO_L42P_YY	E20
1	IO_L43N_Y	A23
1	IO_L43P_Y	D21
1	IO_WRITE_L44N_YY	C22
1	IO_CS_L44P_YY	E21
2	IO	D25[1]
2	IO	D26
2	IO	E26
2	IO	F26
2	IO	H26[1]
2	IO	K26[1]
2	IO	M25[1]
2	IO	N26[1]
2	IO_D1	K24
2	IO_DOUT_BUSY_L45P_YY	E23
2	IO_DIN_D0_L45N_YY	F22
2	IO_L46P_YY	E24
2	IO_L46N_YY	F20
2	IO_L47P_Y	G21
2	IO_L47N_Y	G22
2	IO_VREF_L48P_Y	F24
2	IO_L48N_Y	H20
2	IO_L49P_Y	E25
2	IO_L49N_Y	H21
2	IO_L50P_YY	F23
2	IO_L50N_YY	G23
2	IO_VREF_L51P_YY	H23
2	IO_L51N_YY	J20
2	IO_L52P_YY	G24
2	IO_L52N_YY	H22
2	IO_L53P_Y	J21
2	IO_L53N_Y	G25

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
2	IO_VREF_L54P_Y	G26[2]
2	IO_L54N_Y	J22
2	IO_L55P_YY	H24
2	IO_L55N_YY	J23
2	IO_L56P_YY	J24
2	IO_VREF_L56N_YY	K20
2	IO_D2_L57P_YY	K22
2	IO_L57N_YY	K21
2	IO_L58P_YY	H25
2	IO_L58N_YY	K23
2	IO_L59P_Y	L20
2	IO_L59N_Y	J26
2	IO_L60P_Y	K25
2	IO_L60N_Y	L22
2	IO_L61P_Y	L21
2	IO_L61N_Y	L23
2	IO_L62P_Y	M20
2	IO_L62N_Y	L24
2	IO_VREF_L63P_YY	M23
2	IO_D3_L63N_YY	M22
2	IO_L64P_YY	L26
2	IO_L64N_YY	M21
2	IO_L65P_Y	N19
2	IO_L65N_Y	M24
2	IO_VREF_L66P_Y	M26
2	IO_L66N_Y	N20
2	IO_L67P_YY	N24
2	IO_L67N_YY	N21
2	IO_L68P_YY	N23
2	IO_L68N_YY	N22
3	IO	P24
3	IO	P26[1]
3	IO	R26[1]
3	IO	T26[1]
3	IO	U26[1]
3	IO	W25

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
0	IO_VREF_L27N_YY	D27
0	IO_L27P_YY	B25
0	IO_L28N_Y	A25
0	IO_L28P_Y	D26
0	IO_L29N_Y	A24
0	IO_L29P_Y	E25
0	IO_L30N_YY	D25
0	IO_L30P_YY	B24
0	IO_VREF_L31N_YY	E24
0	IO_L31P_YY	A23
0	IO_L32N_Y	C23
0	IO_L32P_Y	E23
0	IO_VREF_L33N_Y	B23[1]
0	IO_L33P_Y	D23
0	IO_LVDS_DLL_L34N	A22
1	GCK2	B22
1	IO	A14
1	IO	A20
1	IO	B11
1	IO	B13
1	IO	C8
1	IO	C18
1	IO	C21
1	IO	D7
1	IO	D10
1	IO	D15
1	IO	D17
1	IO	E20
1	IO_LVDS_DLL_L34P	D22
1	IO_L35N_Y	D21
1	IO_VREF_L35P_Y	B21[1]
1	IO_L36N_Y	D20
1	IO_L36P_Y	A21
1	IO_L37N_YY	C20
1	IO_VREF_L37P_YY	D19
1	IO_L38N_YY	B20

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
1	IO_L38P_YY	E19
1	IO_L39N_Y	D18
1	IO_L39P_Y	A19
1	IO_L40N_Y	E18
1	IO_L40P_Y	C19
1	IO_L41N_YY	B19
1	IO_VREF_L41P_YY	E17
1	IO_L42N_YY	A18
1	IO_L42P_YY	D16
1	IO_L43N_Y	E16
1	IO_L43P_Y	B18
1	IO_L44N_Y	F16
1	IO_L44P_Y	A17
1	IO_L45N_YY	C17
1	IO_VREF_L45P_YY	E15
1	IO_L46N_YY	B17
1	IO_L46P_YY	D14
1	IO_L47N_Y	A16
1	IO_L47P_Y	E14
1	IO_L48N_Y	C16
1	IO_L48P_Y	D13
1	IO_L49N_Y	B16
1	IO_L49P_Y	D12
1	IO_L50N_Y	A15
1	IO_L50P_Y	E12
1	IO_L51N_YY	C15
1	IO_L51P_YY	C11
1	IO_L52N_YY	B15
1	IO_VREF_L52P_YY	D11
1	IO_L53N_Y	E11
1	IO_L53P_Y	C14
1	IO_L54N_Y	C10
1	IO_L54P_Y	B14
1	IO_L55N_YY	A13
1	IO_VREF_L55P_YY	E10
1	IO_L56N_YY	C13
1	IO_L56P_YY	C9

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
3	IO_L117N_Y	AJ5
3	IO_L118P	AG2
3	IO_L118N	AK4
3	IO_L119P_Y	AG3
3	IO_L119N_Y	AL4
3	IO_L120P_Y	AH1
3	IO_L120N_Y	AL5
3	IO_L121P_Y	AH2
3	IO_L121N_Y	AM4
3	IO_L122P_YY	AH3
3	IO_D5_L122N_YY	AM5
3	IO_D6_L123P_YY	AJ1
3	IO_VREF_L123N_YY	AN3
3	IO_L124P_Y	AN4
3	IO_L124N_Y	AJ3
3	IO_L125P_YY	AN5
3	IO_L125N_YY	AK1
3	IO_L126P_YY	AK2
3	IO_VREF_L126N_YY	AP4
3	IO_L127P_Y	AK3
3	IO_L127N_Y	AP5
3	IO_L128P_Y	AR3
3	IO_VREF_L128N_Y	AL2[2]
3	IO_L129P_YY	AR4
3	IO_L129N_YY	AL3
3	IO_L130P_YY	AM1
3	IO_VREF_L130N_YY	AT3
3	IO_L131P_Y	AM2
3	IO_L131N_Y	AT4
3	IO_L132P_Y	AT5
3	IO_L132N_Y	AN1
3	IO_L133P_YY	AU3
3	IO_L133N_YY	AN2
3	IO_L134P_Y	AP1
3	IO_VREF_L134N_Y	AP2
3	IO_L135P_Y	AR1
3	IO_L135N_Y	AV3

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
3	IO_L136P	AR2
3	IO_L136N	AT1
3	IO_L137P_Y	AV4
3	IO_VREF_L137N_Y	AT2
3	IO_L138P_Y	AU1
3	IO_L138N_Y	AU5
3	IO_L139P_Y	AU2
3	IO_L139N_Y	AW3
3	IO_D7_L140P_YY	AV1
3	IO_INIT_L140N_YY	AW5
4	GCK0	BA22
4	IO	AV17
4	IO	AY11
4	IO	AY12
4	IO	AY13
4	IO	AY14
4	IO	BA8
4	IO	BA17
4	IO	BA19
4	IO	BA20
4	IO	BA21
4	IO	BB9
4	IO	BB18
4	IO_L141P_YY	AV6
4	IO_L141N_YY	BA4
4	IO_L142P_Y	AY4
4	IO_L142N_Y	BA5
4	IO_L143P_Y	AW6
4	IO_L143N_Y	BB5
4	IO_VREF_L144P_Y	BA6
4	IO_L144N_Y	AY5
4	IO_L145P_Y	BB6
4	IO_L145N_Y	AY6
4	IO_L146P_YY	BA7
4	IO_L146N_YY	AV7
4	IO_VREF_L147P_YY	BB7

Table 25: **FG860 Differential Pin Pair Summary XCV1000E, XCV1600E, XCV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
188	5	AY27	AV28	√	-
189	5	BA27	AW29	5	-
190	5	BB28	AV29	1	-
191	5	AY28	AW30	1	-
192	5	BA28	AW31	2	-
193	5	BB29	AV31	√	-
194	5	AY29	AY32	√	VREF
195	5	AW32	BB30	2	-
196	5	AV32	AY30	2	-
197	5	BA30	AW33	√	VREF
198	5	BB31	AV33	√	-
199	5	AY34	BA31	1	VREF
200	5	AW34	BB32	1	-
201	5	BA32	AY35	√	VREF
202	5	BB33	AW35	√	-
203	5	AV35	BB34	5	-
204	5	AY36	BA34	5	-
205	5	BB35	AV36	√	VREF
206	5	BA35	AY37	√	-
207	5	BB36	BA36	5	-
208	5	AW37	BB37	1	VREF
209	5	BA37	AY38	1	-
210	5	BB38	AY39	2	-
211	6	AV42	AV41	√	-
212	6	AU41	AW40	3	-
213	6	AU42	AV39	1	-
214	6	AU38	AT41	2	VREF
215	6	AV40	AT42	4	-
216	6	AU39	AR41	2	-
217	6	AU40	AR42	1	VREF
218	6	AP42	AT38	√	-
219	6	AT39	AN41	2	-
220	6	AM40	AT40	1	-
221	6	AM41	AR38	√	VREF
222	6	AR40	AM42	√	-
223	6	AP38	AL40	5	VREF
224	6	AL42	AP39	2	-
225	6	AK40	AP40	√	VREF
226	6	AN39	AK41	√	-
227	6	AN40	AK42	2	-
228	6	AJ41	AM38	√	VREF
229	6	AM39	AJ42	√	-
230	6	AH41	AH40	3	-
231	6	AH42	AL38	1	-
232	6	AG41	AL39	2	-
233	6	AG40	AK39	4	-
234	6	AG42	AJ38	2	-
235	6	AJ39	AF42	1	VREF
236	6	AH38	AF41	√	-
237	6	AH39	AE42	2	-
238	6	AE41	AG38	1	-
239	6	AD42	AG39	√	VREF
240	6	AF39	AD40	√	-
241	6	AE38	AD41	5	-
242	6	AC40	AE39	2	-
243	6	AC41	AD38	√	VREF
244	6	AC38	AB42	√	-
245	6	AC39	AB40	2	VREF
246	7	AB39	AA41	√	-
247	7	AA39	Y41	2	VREF
248	7	Y39	Y40	√	-
249	7	W41	Y38	√	VREF
250	7	W39	W40	2	-
251	7	V41	W38	5	-
252	7	V40	V39	√	-
253	7	U39	V42	√	VREF
254	7	U38	U41	1	-
255	7	T39	U42	2	-

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
256	7	N6	M6	1	-
257	7	N1	N5	4	-
258	7	M5	M4	√	-
259	7	M1	M2	1	VREF
260	7	L2	L4	4	-
261	7	L5	M7	3	-
262	7	M8	L1	4	-
263	7	M9	K2	1	-
264	7	M10	L3	NA	-
265	7	K1	K5	√	-
266	7	K3	L6	√	VREF
267	7	K4	L7	4	-
268	7	J5	L8	4	-
269	7	H4	K6	4	VREF
270	7	K7	H1	4	-
271	7	J2	J7	2	-
272	7	G2	H5	√	-
273	7	G5	L9	√	VREF
274	7	K8	F3	1	-
275	7	E1	G3	4	-
276	7	E2	H6	√	-
277	7	K9	E4	1	VREF
278	7	F4	J8	4	-
279	7	H7	D1	3	-
280	7	C2	G6	4	VREF
281	7	F5	D2	1	-
282	7	K10	D3	4	-

Notes:
1. AO in the XCV600E, 1000E.
2. AO in the XCV1000E.
3. AO in the XCV1600E.
4. AO in the XCV1000E, XCV1600E.

FG1156 Fine-Pitch Ball Grid Array Package

XCV1000E, XCV1600E, XCV2000E, XCV2600E, and XCV3200E devices in the FG1156 fine-pitch Ball Grid Array package have footprint compatibility. Pins labeled IO_VREF can be used as either V_{REF} or general I/O, unless indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 28, see Table 29 for Differential Pair information.

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
0	GCK3	E17
0	IO	B4
0	IO	B9
0	IO	B10
0	IO	D9[3]
0	IO	D16
0	IO	E7[3]
0	IO	E11[3]
0	IO	E13[3]
0	IO	E16[3]
0	IO	F17[3]
0	IO	J12[3]
0	IO	J13[3]
0	IO	J14[3]
0	IO	K11[3]
0	IO_L0N_Y	F7
0	IO_L0P_Y	H9
0	IO_L1N_Y	C5
0	IO_L1P_Y	J10
0	IO_VREF_L2N_Y	E6
0	IO_L2P_Y	D6
0	IO_L3N_Y	A4
0	IO_L3P_Y	G8
0	IO_L4N_YY	C6
0	IO_L4P_YY	J11
0	IO_VREF_L5N_YY	G9
0	IO_L5P_YY	F8
0	IO_L6N_YY	A5[4]

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
2	IO_L126N_YY	T32
2	IO_VREF_L127P_Y	U29[1]
2	IO_L127N_Y	U33
2	IO_L128P_YY	V33
2	IO_L128N_YY	U31
3	IO	V27[3]
3	IO	V31
3	IO	V32[3]
3	IO	W33
3	IO	AB25[3]
3	IO	AB26[3]
3	IO	AB31[3]
3	IO	AC31[3]
3	IO	AF34
3	IO	AG31[3]
3	IO	AG33[3]
3	IO	AG34
3	IO	AH29[3]
3	IO	AJ30[3]
3	IO_L129P_Y	V26
3	IO_VREF_L129N_Y	V30[1]
3	IO_L130P_YY	W34
3	IO_L130N_YY	V28
3	IO_L131P_YY	W32
3	IO_VREF_L131N_YY	W30
3	IO_L132P_Y	V29
3	IO_L132N_Y	Y34
3	IO_L133P	W29[5]
3	IO_L133N	Y33[4]
3	IO_L134P_Y	W26
3	IO_L134N_Y	W28
3	IO_L135P_YY	Y31
3	IO_L135N_YY	Y30

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
3	IO_L136P_YY	AA34[5]
3	IO_L136N_YY	W31[4]
3	IO_D4_L137P_YY	AA33
3	IO_VREF_L137N_YY	Y29
3	IO_L138P_Y	W25
3	IO_L138N_Y	AB34
3	IO_L139P_Y	Y28[5]
3	IO_L139N_Y	AB33[4]
3	IO_L140P_Y	AA30
3	IO_L140N_Y	Y26
3	IO_L141P_YY	Y27
3	IO_L141N_YY	AA31
3	IO_L142P_YY	AA27[5]
3	IO_L142N_YY	AA29[4]
3	IO_L143P_Y	AB32
3	IO_VREF_L143N_Y	AB29
3	IO_L144P_Y	AA28
3	IO_L144N_Y	AC34
3	IO_L145P	Y25
3	IO_L145N	AD34
3	IO_L146P_Y	AB30
3	IO_L146N_Y	AC33
3	IO_L147P_Y	AA26
3	IO_L147N_Y	AC32
3	IO_L148P_Y	AD33
3	IO_L148N_Y	AB28
3	IO_L149P_YY	AE34
3	IO_D5_L149N_YY	AB27
3	IO_D6_L150P_YY	AE33
3	IO_VREF_L150N_YY	AC30
3	IO_L151P_Y	AA25
3	IO_L151N_Y	AE32
3	IO_L152P_YY	AE31
3	IO_L152N_YY	AD29

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
111	2	M31	R26	2600 1600	-
112	2	N30	P28	3200 1600 1000	-
113	2	N29	N33	2600 2000 1000	VREF
114	2	T25	N34	3200 2600 2000 1600	-
115	2	P34	R27	3200 2600 2000 1600 1000	-
116	2	P29	P31	3200 2600 1600 1000	-
117	2	P33	T26	3200 2600 2000	-
118	2	R34	R28	2600 2000 1000	-
119	2	N31	N32	2000 1600 1000	D3
120	2	P30	R33	2000 1600	-
121	2	R29	T34	3200 2600 2000 1600 1000	-
122	2	R30	T30	1000	-
123	2	T28	R31	3200 1600	-
124	2	T29	U27	3200 2600 1600 1000	-
125	2	T31	T33	2000 1600 1000	VREF
126	2	U28	T32	2000 1600 1000	-
127	2	U29	U33	3200 2600 1600 1000	VREF
128	2	V33	U31	3200 2600 2000 1600 1000	-
129	3	V26	V30	3200 2600 1600 1000	VREF
130	3	W34	V28	2000 1600 1000	-
131	3	W32	W30	2000 1600 1000	VREF

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
132	3	V29	Y34	3200 2600 1600 1000	-
133	3	W29	Y33	3200 1600	-
134	3	W26	W28	1000	-
135	3	Y31	Y30	3200 2600 2000 1600 1000	-
136	3	AA34	W31	2000 1600	-
137	3	AA33	Y29	2000 1600 1000	VREF
138	3	W25	AB34	2600 2000 1000	-
139	3	Y28	AB33	3200 2600 2000	-
140	3	AA30	Y26	3200 2600 1600 1000	-
141	3	Y27	AA31	3200 2600 2000 1600 1000	-
142	3	AA27	AA29	3200 2600 2000 1600	-
143	3	AB32	AB29	2600 2000 1000	VREF
144	3	AA28	AC34	3200 1600 1000	-
145	3	Y25	AD34	2600 1600	-
146	3	AB30	AC33	3200 2600 1600 1000	-
147	3	AA26	AC32	2000 1000	-
148	3	AD33	AB28	3200 2600 2000	-
149	3	AE34	AB27	3200 2600 2000 1600 1000	D5
150	3	AE33	AC30	2000 1600 1000	VREF
151	3	AA25	AE32	3200 1600 1000	-
152	3	AE31	AD29	3200 2600 2000 1600 1000	-